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<th>BOARD #: T302-08627</th>
<th>PINS E1</th>
<th>S110 PIN# Not In VersionControl</th>
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<tr>
<td>LAYER NAME = Top Layer</td>
<td>VID No. T302-08627</td>
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<td>4:20:32 PM</td>
<td>TEXAS INSTRUMENTS</td>
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<tr>
<td>LAYER NAME: Bottom Overlay</td>
<td>TID: TID00-00007</td>
<td>PEN: E1</td>
<td>SHM Penn Not In VersionControl</td>
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<td>PEN E1</td>
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**NOTE:**
- **BOMD # TID00-00007**
- **PEN: E1**
- **SHM Penn Not In VersionControl**
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